

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S4	99	"4983251"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/13 13:14
S5	2	("4983251").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/02/13 13:26
S6	5	"2003021705"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/13 13:27
S7	3	"20030211705"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/13 13:28
S8	17430	(Bond\$3 adhes\$3) with silicon with oxide	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/13 13:55
S9	3764	(Bond\$3 adhes\$3) with silicon with oxide and stack\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/13 13:56
S10	2624	(Bond\$3 adhes\$3) with silicon with oxide and stack\$3 and heat \$3 and (thin\$4 CMP etch\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/13 13:56

S12	83	(Bond\$3 adhes\$3) with silicon with oxide and stack\$3 and heat \$3 and (thin\$4 CMP etch\$3) and clean\$3 and polymer with cross \$1link\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/13 13:58
S13	16	(Bond\$3 adhes\$3) with silicon with oxide and stack\$3 and heat \$3 and (planneriz\$3 thin\$4 CMP etch\$3) with (cross\$1link\$3) and clean\$3 and polymer and cross \$1link\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/13 19:20
S14	3245	438/118	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/13 20:50
S15	10	S14 and silicon with oxide with adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/13 20:51
S16	11	438/406 and silicon with oxide with adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/13 20:52
S17	1261	(Bond\$3 adhes\$3) with silicon with oxide and stack\$3 and heat \$3 and (thin\$4 CMP etch\$3) and clean\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/15 15:05

2/19/2008 11:24:52 AM

C:\Documents and Settings\Snikmanesh\My Documents\EAST\Workspaces\10581111.wsp